

SN100C & SN100Ce

SN100C(Sn-Cu+Ni)含有少量的鎳，且與傳統的錫—鉛共晶焊錫具有同等之流動性。故不僅可抑制錫橋，在貫通孔基板上也有頗佳之爬錫性。優異之焊接接合特性(無論是作業性、信賴性)，且不含高價貴金屬之銀，可再生循環使用，錫渣產生量低，因而能有漂亮價格的表現。還有報告指出於音響成品上，SN100C可以提升音質。SN100Ce是用於調整SN100C的銅成分焊錫。

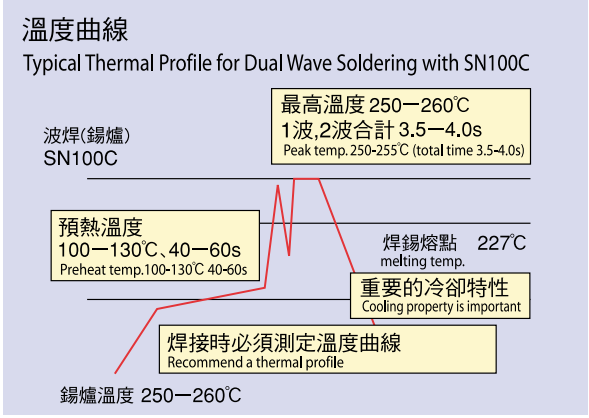
Experience in commercial mass production over six years has confirmed that SN100C Sn-Cu+Ni alloy, with the complementary top-up alloy SN100Ce reliably provides bridge-free soldering. The patented Ni addition improves the wetting and flow of the alloy facilitating through-hole penetration, fillet formation and drainage of excess solder from the board. Performance is at least comparable with that of more expensive silver-containing alloys and joints are smoother and brighter. It has even been reported that the sound quality audio system is better because of higher electrical conductivity.

焊接測試受理中
Always welcome for soldering test

Send your printed board assembly to our Osaka Headquarters and we will be pleased to wave solder it with SN100C and return it. Please contact with us in detail.



SN100C波峰焊接
Wave soldering with SN100C
QFP100 pins 0.65mm pitch

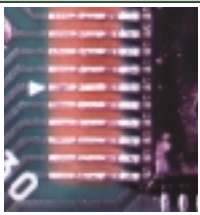
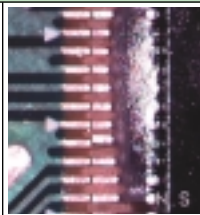
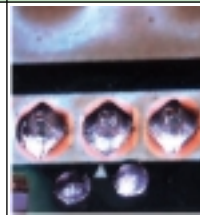
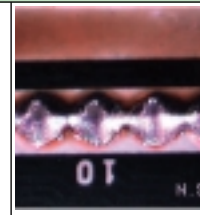


添加鎳的效果

Beneficial Effect of Nickel Additions on the As-Cast surface of Sn-Cu Eutectic Alloy

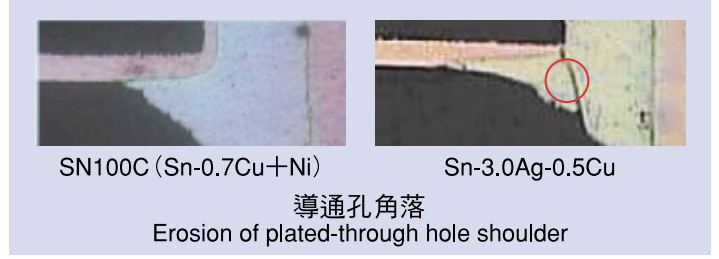
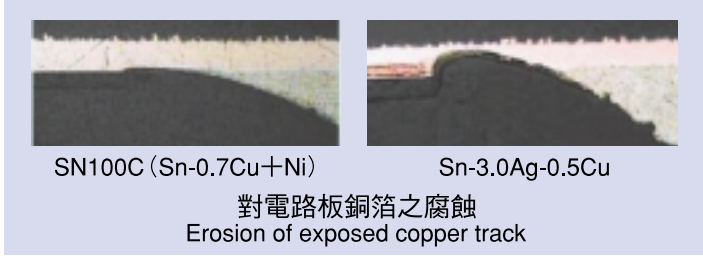
SN100C中含有的鎳，可提高焊錫的流動性，減少架橋與錫柱、錫尖等不良現象。

Trace addition of Nickel into SN100C enhances fluidity, thus reducing the formation of bridges, icicles.

QFP		連接器 Connector	
			
SN100C (Sn-Cu+Ni)	Sn-0.7Cu	SN100C (Sn-Cu+Ni)	Sn-0.7Cu

因焊錫合金導致腐蝕現象之比較

Less Copper Erosion with SN100C



○ 導通孔角落銅箔被腐蝕後、導致應力強度減弱、故於熱循環振動後發生龜裂。
Erosion of plated-through hole shoulder results in cracking during thermal cycling.